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DOCKET NO. PTGF-04001

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AMENDMENTS TO THE CLAIMS:

Claim 1. (Previously presented) A light emitting diode (LED) lamp, comprising:

a package; and

a plurality of light emitting elements that are electrically connected to a plurality of electrode plates provided in the package and that are sealed with transparent material, wherein a red light emitting element of the plurality of light emitting elements is wire bonded along a longitudinal direction of the package, a green light emitting element and a blue light emitting element are flip-chip bonded face down directly to a first electrode of the plurality of electrodes, and wherein the plurality of electrodes extend to a surface opposite to a light emission surface of the LED lamp while being embedded in the package.

Claim 2. (Previously presented) The LED lamp according to claim 1, wherein the red light emitting element comprises a plurality of red light emitting elements, and every two of the plurality of red light emitting elements are connected in series.

Claim 3. (Previously presented) The LED lamp according to claim 1, wherein the package comprises a ceramics material.

Claims 4-10. (Canceled).

Claim 11. (Previously presented) The LED lamp of claim 1, wherein said red light emitting element is bonded to said first electrode of the plurality of electrodes.

Claim 12. (Previously presented) The LED lamp of claim 1, wherein said red light emitting element is wire bonded to a second electrode of said plurality of electrodes.

Claim 13. (Previously presented) The LED lamp of claim 12, wherein said plurality of light emitting elements further comprises another red light emitting element bonded to a third electrode of said plurality of electrodes and wire bonded to a fourth electrode of said plurality of electrodes.

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Claim 14. (Previously presented) The LED lamp of claim 1, wherein each of the plurality of electrodes extends from said light emitting surface of said package to said surface opposite to said light emitting surface through a through hole extending through said package.

Claim 15. (Previously presented) The LED lamp of claim 1, wherein said package comprises a board that defines said surface opposite said light emission surface and a surface on which said plurality of electrodes are provided.

Claim 16. (Previously presented) The LED lamp of claim 15, wherein said board comprises a glass epoxy board.

Claim 17. (Previously presented) The LED lamp of claim 1, wherein said package comprises a stack of a plurality of thin plate members.

Claim 18. (Previously presented) The LED lamp of claim 1, wherein said package comprises a stack of three thin plate members.

Claim 19. (Previously presented) The LED lamp of claim 1, wherein said package defines a plurality of cutting regions at a boundary of the plurality of electrodes on said surface opposite to the light emission surface.

Claim 20. (Previously presented) The LED lamp of claim 19, wherein each of the plurality of cutting regions corresponds to one of the plurality of electrodes.

Claim 21. (Previously presented) The LED lamp of claim 19, wherein said at least one of the plurality of cutting regions comprises a rectangular cutting region.

Claim 22. (Previously presented) The LED lamp of claim 1, wherein said package defines an opening in which said plurality of light emitting elements are received.

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Claim 23. (Previously presented) The LED lamp of claim 22, wherein said plurality of light emitting elements are aligned along a central longitudinal axis of said opening in said package.

Claim 24. (Previously presented) The LED lamp of claim 1, wherein said package comprises a plating portion at each corner of said package.

Claim 25. (Currently amended) A light emitting diode (LED) lamp comprising:
a package;
a plurality of electrodes in an opening in said package;
a red light emitting element bonded to a first electrode of said plurality of electrodes;
a green light emitting element directly flip-chip bonded face down to said first electrode; and
a blue light emitting element directly flip-chip bonded face down to said first electrode.